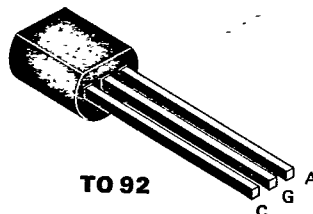


8834750 TAG SEMICONDUCTORS LTD

63C 00674 DT-25-11

TAG SEMICONDUCTORS LTD


**X0103BA –
X0103NA SCR'S**
0.8 A 200–800 V 20–200 μ A

The X0103 series silicon controlled rectifiers are high performance PNP devices diffused with TAG's proprietary Top Glass™ Process. These parts are intended for general purpose, high speed, high voltage applications.

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Part Nr.	Symbol	Min.	Max.	Unit	Test Conditions
Repetitive Peak Off State Voltage	X0103BA	[V_{DRM} V_{RRM}]	200		V	[$T_J = -40^\circ\text{C}$ to 125°C $R_{GK} = 1\text{K}\Omega$]
	X0103DA		400		V	
	X0103MA		600		V	
	X0103NA		800		V	
On-State Current		$I_{T(RMS)}$	0.8		A	All Conduction Angles $T_C = 55^\circ\text{C}$
Average On-State Current		$I_{T(AV)}$	0.5		A	Half Cycle, $\Theta = 180^\circ$, $T_C = 55^\circ\text{C}$
Nonrept. On-State Current		I_{TSM}	9		A	Half Cycle, 60 Hz
Nonrept. On-State Current		I_{TSM}	8		A	Half Cycle, 50 Hz
Fusing Current		I_{ft}	0.32		A ² s	$t = 10\text{ ms}$, Half Cycle
Peak Reverse Gate Voltage		V_{GRM}	8		V	$I_{GR} = 10\mu\text{A}$
Peak Gate Current		I_{GM}	1		A	10 μs max.
Peak Gate Dissipation		P_{GM}	2		W	10 μs max.
Gate Dissipation		$P_{G(AV)}$	0.1		W	20 ms max.
Operating Temperature		T_J	-55	125	$^\circ\text{C}$	
Storage Temperature		T_{stg}	-65	150	$^\circ\text{C}$	
Soldering Temperature		T_{sld}		250	$^\circ\text{C}$	1.6 mm from case, 10 s max.

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Min.	Max.	Unit	Test Conditions
Off-State Leakage Current	I_{DRM}/I_{RRM}		0.1	mA	@ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 125^\circ\text{C}$
Off-State Leakage Current	I_{DRM}/I_{RRM}		5	μA	@ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 25^\circ\text{C}$
On-State Voltage	V_T		1.50	V	at $I_T = 1.6\text{ A}$, $T_J = 25^\circ\text{C}$
On-State Threshold Voltage	$V_{T(TO)}$		0.9	V	$T_J = 125^\circ\text{C}$
On-State Slope Resistance	r_T		400	m Ω	$T_J = 125^\circ\text{C}$
Gate Trigger Current	I_{GT}	20	200	μA	$V_D = 7\text{ V}$
Gate Trigger Voltage	V_{GT}		0.8	V	$V_D = 7\text{ V}$
Holding Current	I_H		5	mA	$R_{GK} = 1\text{K}\Omega$
Latching Current	I_L		6	mA	$R_{GK} = 1\text{K}\Omega$
Critical Rate of Voltage Rise	dv/dt	100		V/ μs	$V_D = .67 \times V_{DRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 125^\circ\text{C}$
Critical Rate of Current Rise	di/dt	30		A/ μs	$I_G = 10\text{ mA}$, $di/dt = 0.1\text{ A}/\mu\text{s}$, $T_J = 125^\circ\text{C}$
Gate Controlled Delay Time	t_{gd}		1.0	μs	$I_G = 10\text{ mA}$, $di/dt = 0.1\text{ A}/\mu\text{s}$
Commutated Turn-Off Time	t_q		100	μs	$T_C = 85^\circ\text{C}$, $V_D = .67 \times V_{DRM}$, $V_R = 35\text{ V}$, $I_T = I_{T(AV)}$
Thermal Resistance junc. to case	$R_{\theta jc}$		100	K/W	
Thermal Resistance junc. to amb.	$R_{\theta ja}$		200	K/W	